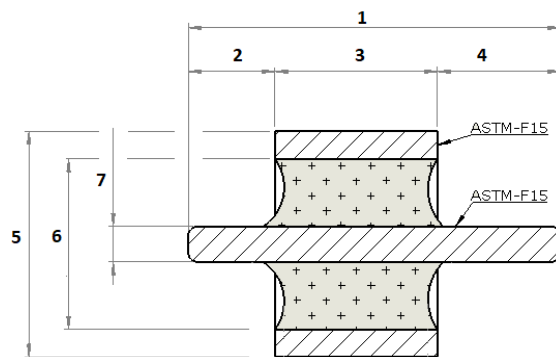


GLASS BEADS & CONNECTORS (GLASS TO METAL SEALING)

- RF Glass Beads/Feedthroughs

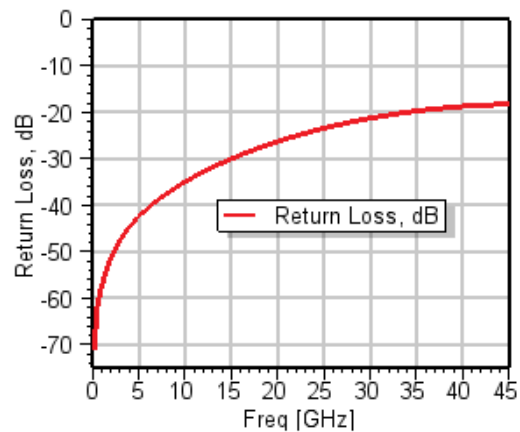
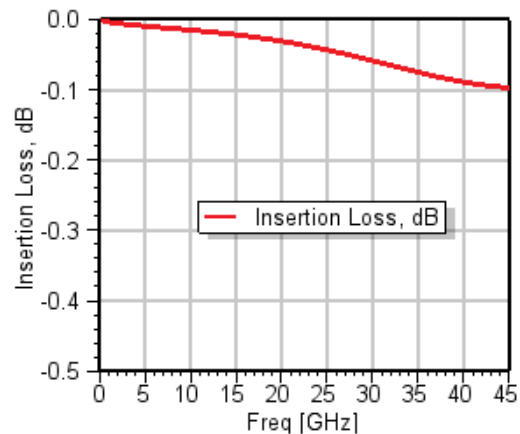


Hermetic RF feedthroughs/glass bead (K100, V100).
An ideal choice for high-density packaging and multiport applications, with option to mount as feedthroughs or integrated as a standard connector.



Part n°	1	2	3	4	5	6	7
EATR	mm	mm	mm	mm	mm	mm	mm
01509902252	5.72	2.36	1.52	1.84	2.52	2.06	0.38
0120990133	3.39	0.74	1.60	1.05	2.52	1.62	0.30
01207601255	3.18	0.74	1.39	1.05	1.92	1.45	0.30
0120990186	4.73	1.83	1.60	1.30	2.52	1.62	0.30
00906801101	2.79	0.66	1.40	0.73	1.73	1.22	0.24

RF Simulation Results



Unless otherwise specified:

Center conductor: ASTM-F15 (KOVAR),
1.27µm to 3.81µm Gold plated over 1.27µm
to 3.81µm nickel.

Outside conductor: ASTM-F15 (KOVAR),
1.27µm to 3.81µm Gold plated over 1.27µm
to 3.81µm nickel.

Glass: CORNING 7070.

RF perf: 50 ±3ohms, 45GHz

Seal: hermetic at 10⁻⁸ atm.cm3/s



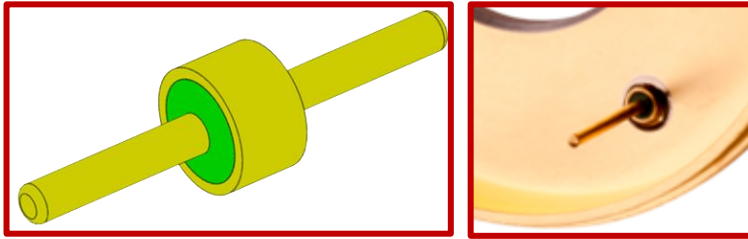
CONTACTS :

EGIDE France : sales@fr.egide-group.com

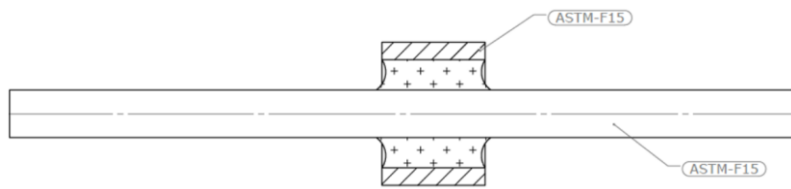
EGIDE USA : sales@us.egide-group.com

www.egide-group.com

• **DC Glass Beads/Feedthroughs**



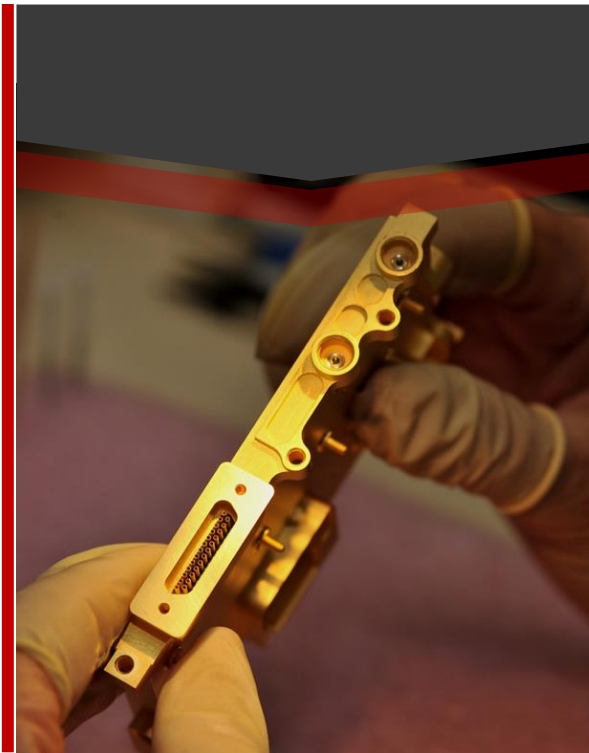
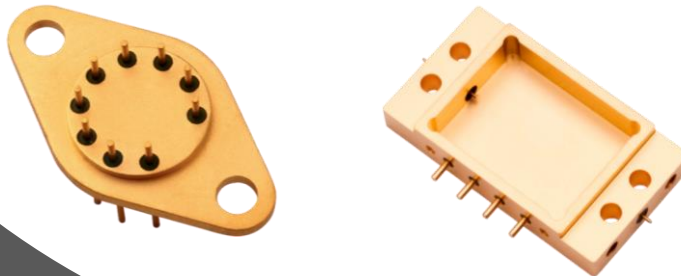
Wide range of hermetic DC and power feedthroughs (EATD/EATP). Applications: High density and multipoint packaging/housing for space, telecom, military products and systems.



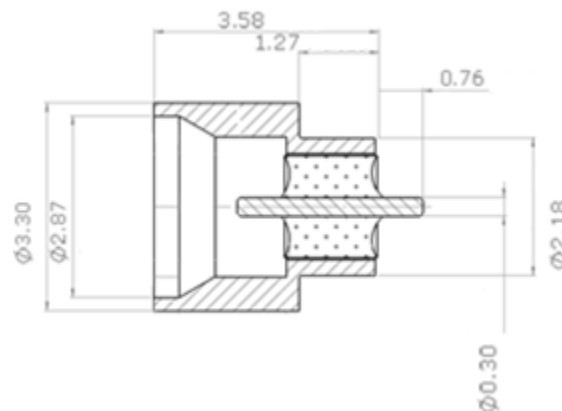
Both center and outside conductor:

ASTM-F15 (KOVAR), 1.27µm to 3.81µm Gold plated over 1.27µm to 3.81µm nickel.

Hermetic at 10⁻⁸ atm.cm³/s.



• **SMPM Connector:**



Center conductor: ASTM-F15 (KOVAR), 1.27µm to 3.81µm Gold plated over 1.27µm to 3.81µm nickel.

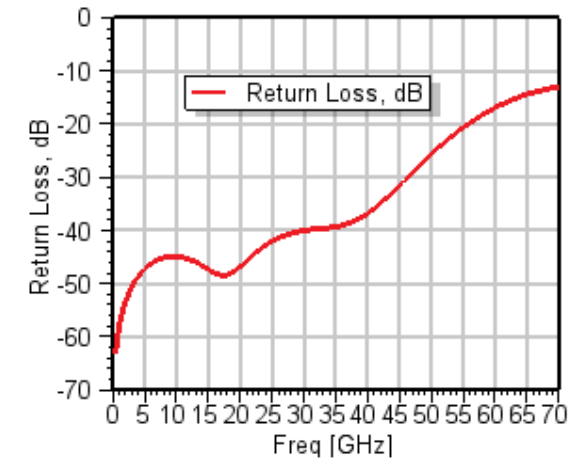
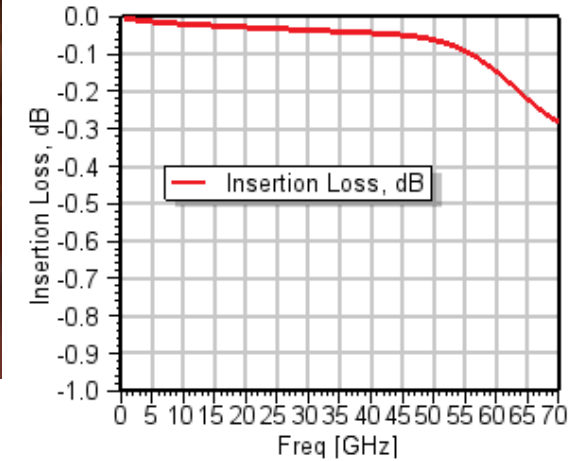
Outside conductor: ASTM-F15 (KOVAR), 1.27µm to 3.81µm Gold plated over 1.27µm to 3.81µm nickel.

RF perf: 50 ohms, DC-65GHz.

Glass: CORNING 7070.

Seal: hermetic at 10⁻⁸ atm.cm³/s

RF Simulation Results



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